



GA6 'N*', 5E'H<F I'GA6 'N&&\$5E'

G i fZUWY' Ac i bh'NYbYf' 8]cXYg''

..... : YU h i fYg''

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Part no. with suffix "Q" means AEC-Q101 qualified

..... AYW\Ub]WU'' 8UhU'

- DUW_U[Y: DO-214AA (SMB)
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- HYf a]bU'g': Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Dc`Uf]hm. Cathode line denotes the cathode end

AUI]a i a'FUh]b[g (Ta=25 Unless otherwise specified)

D5F5A9H9F'	GMA6C@'	I B-H'	A5L'
DC power dissipation at T _L = 75 °C	P _D	W	3.0
Maximum instantaneous forward voltage@ I _F =200mA	V _F	V	1.5
Maximum junction temperature	T _J		-55 to +150

Storage temperature range

T_{stg}

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$$60\% = \$47 + 58 \quad 60\% = \$4$$

v2UGHULQJ ,QIRUPDWRQ

35() (5(' 3 1	3\$&.,1* &2' (81,7 : (, *+7 J	0,1,080 3\$&.\$*(SFV	287(5 &\$5721 48\$17,7< SFV	'(/,9(5< 02' (
60% = \$4 a60% =	\$4)				

' UHH

v0DUNLQJ ,QIRUPDWLRQ

v2XWOLQH 'LPHQVLRQV

	'2	\$\$ 60%
	OLQ	OD
\$		

v 6XJJHVWHG SDG OD\RXW

